

In The Claims:

1-230. (canceled)

5 231. (currently amended) ~~A circuitry~~ An electric component comprising:
a first die having a top surface at a horizontal level;
a bottommost metal layer over said horizontal level and extending to a place not
over said first die, wherein said bottommost metal layer is connected to said first die; and
a passive device over said horizontal level.

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232. (currently amended) The ~~circuitry~~ electric component in claim 231 further
comprising a substrate joined with said first die, wherein said substrate is under said
horizontal level.

15 233. (currently amended) The ~~circuitry~~ electric component in claim 232, wherein
said substrate comprises polymer.

234. (currently amended) The ~~circuitry~~ electric component in claim 232, wherein
said substrate comprises resin.

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235. (currently amended) The ~~circuitry~~ electric component in claim 232, wherein
said substrate comprises imide.

236. (currently amended) The ~~circuitry~~ electric component in claim 232, wherein
25 said substrate comprises plastic.

237. (currently amended) The ~~circuitry~~ electric component in claim 232, wherein
said substrate comprises thermosetting plastic.

Claim 238. (canceled)

239. (currently amended) The circuitry ~~electric~~-component in claim 232, wherein forming said substrate comprises ~~is formed using a process comprising~~ pressing.

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240. (currently amended) The circuitry ~~electric~~-component in claim 232, wherein forming said substrate comprises ~~is formed using a process comprising~~ injection molding.

241-242. (canceled)

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243. (currently amended) The circuitry ~~electric~~-component in claim 231 further comprising an insulating layer between said bottommost metal layer and said horizontal level.

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244. (currently amended) The circuitry ~~electric~~-component in claim 243, wherein said insulating layer comprises polyimide (PI).

245. (currently amended) The circuitry ~~electric~~-component in claim 243, wherein said insulating layer comprises benzocyclobutene (BCB).

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246. (currently amended) The circuitry ~~electric~~-component in claim 243, wherein said insulating layer comprises a porous structure.

247. (currently amended) The circuitry ~~electric~~-component in claim 231 further comprising an insulating layer over said bottommost metal layer.

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248. (currently amended) The circuitry ~~electric~~-component in claim 247, wherein said insulating layer comprises polyimide (PI).

249. (currently amended) The circuitry ~~electric~~-component in claim 247, wherein said insulating layer comprises benzocyclobutene (BCB).

5 250. (currently amended) The circuitry ~~electric~~-component in claim 247, wherein said insulating layer comprises a porous structure.

251. (currently amended) The circuitry ~~electric~~-component in claim 231 further comprising an insulating layer between said passive device and said horizontal level.

10 252. (currently amended) The circuitry ~~electric~~-component in claim 251, wherein said insulating layer comprises polyimide (PI).

15 253. (currently amended) The circuitry ~~electric~~-component in claim 251, wherein said insulating layer comprises benzocyclobutene (BCB).

254. (currently amended) The circuitry ~~electric~~-component in claim 251, wherein said insulating layer comprises a porous structure.

20 255. (currently amended) The circuitry ~~electric~~-component in claim 231 further comprising an insulating layer over said passive device.

256. (currently amended) The circuitry ~~electric~~-component in claim 255, wherein said insulating layer comprises polyimide (PI).

25 257. (currently amended) The circuitry ~~electric~~-component in claim 255, wherein said insulating layer comprises benzocyclobutene (BCB).

258. (currently amended) The circuitry ~~electric~~-component in claim 255, wherein said insulating layer comprises a porous structure.

259. (currently amended) The circuitry ~~electric~~-component in claim 231, wherein said top surface comprises multiple pads.

5 260. (currently amended) The circuitry ~~electric~~-component in claim 231, wherein said bottommost metal layer comprises a portion connecting multiple internal circuits of said first die.

10 261. (currently amended) The circuitry ~~electric~~-component in claim 260, wherein said ~~die~~ portion is used to transmit a signal.

262. (currently amended) The circuitry ~~electric~~-component in claim 260, wherein said ~~die~~ portion is used to provide a power voltage.

15 263. (currently amended) The circuitry ~~electric~~-component in claim 260, wherein said ~~die~~ portion is used to provide a ground voltage.

20 264. (currently amended) The circuitry ~~electric~~-component in claim 231 further comprising a second ~~an additional~~ die, said bottommost metal layer being over said second ~~additional~~ die, wherein said bottommost metal layer comprises a portion connecting said first die and said second ~~additional~~ die.

25 265. (currently amended) The circuitry ~~electric~~-component in claim 231 further comprising a film layer around said first die.

266. (currently amended) The circuitry ~~electric~~-component in claim 265, wherein said film layer comprises polymer.

267. (currently amended) The circuitry ~~electric~~ component in claim 265, wherein said film layer comprises epoxy.

5 268. (currently amended) The circuitry ~~electric~~ component in claim 265, wherein said film layer has a surface substantially coplanar with said top surface of said die.

269. (currently amended) The circuitry ~~electric~~ component in claim 231 further comprising a bump over said horizontal level, wherein said bump comprises solder.

10 270. (currently amended) The circuitry ~~electric~~ component in claim 231 further comprising a bump over said horizontal level, wherein said bump comprises gold.

271. (currently amended) The circuitry ~~electric~~ component in claim 231, wherein said passive device comprises a resistor.

15 272. (currently amended) The circuitry ~~electric~~ component in claim 231, wherein said passive device comprises a capacitor.

20 273. (currently amended) The circuitry ~~electric~~ component in claim 231, wherein said passive device comprises an inductor.

274. (currently amended) The circuitry ~~electric~~ component in claim 231, wherein said passive device comprises a filter.

25 275. (currently amended) The circuitry ~~electric~~ component in claim 231, wherein said passive device comprises a waveguide.

276. (currently amended) The circuitry ~~electric~~ component in claim 231, wherein said passive device comprises a micro electronic mechanical sensor (MEMS).

277. (currently amended) The circuitry ~~electric~~-component in claim 231, wherein ~~there is no die under~~ said passive device is not over said first die.

5 278. (currently amended) The circuitry ~~electric~~-component in claim 231, wherein said passive device is connected to a circuit trace of said bottommost metal layer.

279. (currently amended) The circuitry ~~electric~~-component in claim 231, wherein
10 said passive device is connected to said die.

Claims 280-319. (canceled)